

To all our customers

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Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

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# HD74HC563/HD74HC573

Octal Transparent Latches (with 3-state outputs)



ADE-205-509 (Z)  
1st. Edition  
Sep. 2000

## Description

When the latch enable (LE) input is high, the Q outputs of HD74HC563 will follow the inversion of the D inputs and the Q outputs of HD74HC573 will follow the D inputs. When the latch enable goes low, data at the D inputs will be retained at the outputs until latch enable returns high again. When a high logic level is applied to the output control input, all outputs go to a high impedance state, regardless of what signals are present at the other inputs and the state of the storage elements.

## Features

- High Speed Operation:  $t_{pd}$  (Data to Q,  $\overline{Q}$ ) = 11 ns typ ( $C_L = 50$  pF)
- High Output Current: Fanout of 15 LSTTL Loads
- Wide Operating Voltage:  $V_{CC} = 2$  to 6 V
- Low Input Current: 1  $\mu$ A max
- Low Quiescent Supply Current:  $I_{CC}$  (static) = 4  $\mu$ A max ( $T_a = 25^\circ\text{C}$ )

## Function Table

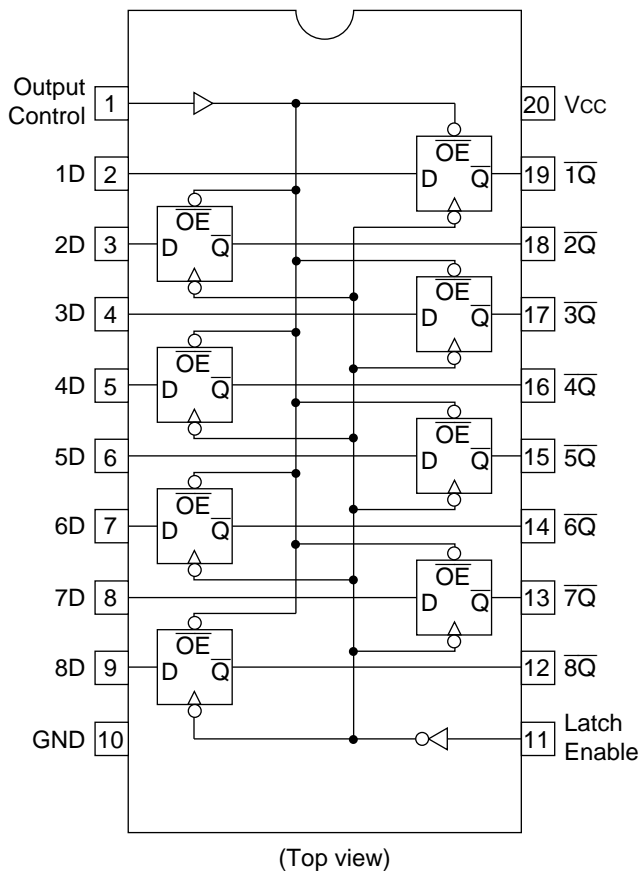
Output Control	Latch Enable	Data	Outputs	
			HD74HC563	HD74HD573
L	H	H	L	H
L	H	L	H	L
L	L	X	$\overline{Q_0}$	$Q_0$
H	X	X	Z	Z

$Q_0$  : level of Q before the indicated Steady-state input conditions were established.

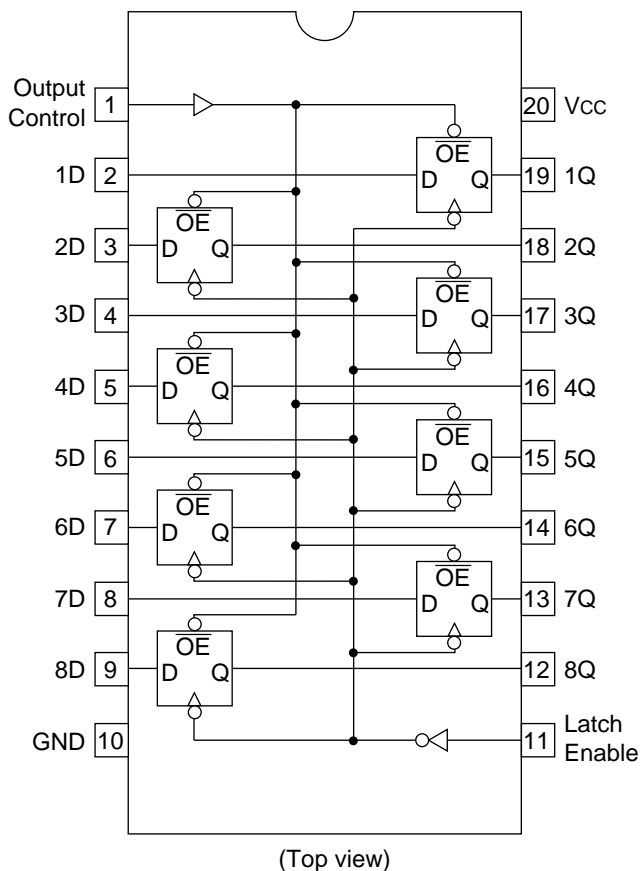
$\overline{Q_0}$  : complement of  $Q_0$  or level of  $\overline{Q}$  before the indicated Steady-state input conditions were established.

## Pin Arrangement

### HD74HC563



HD74HC573

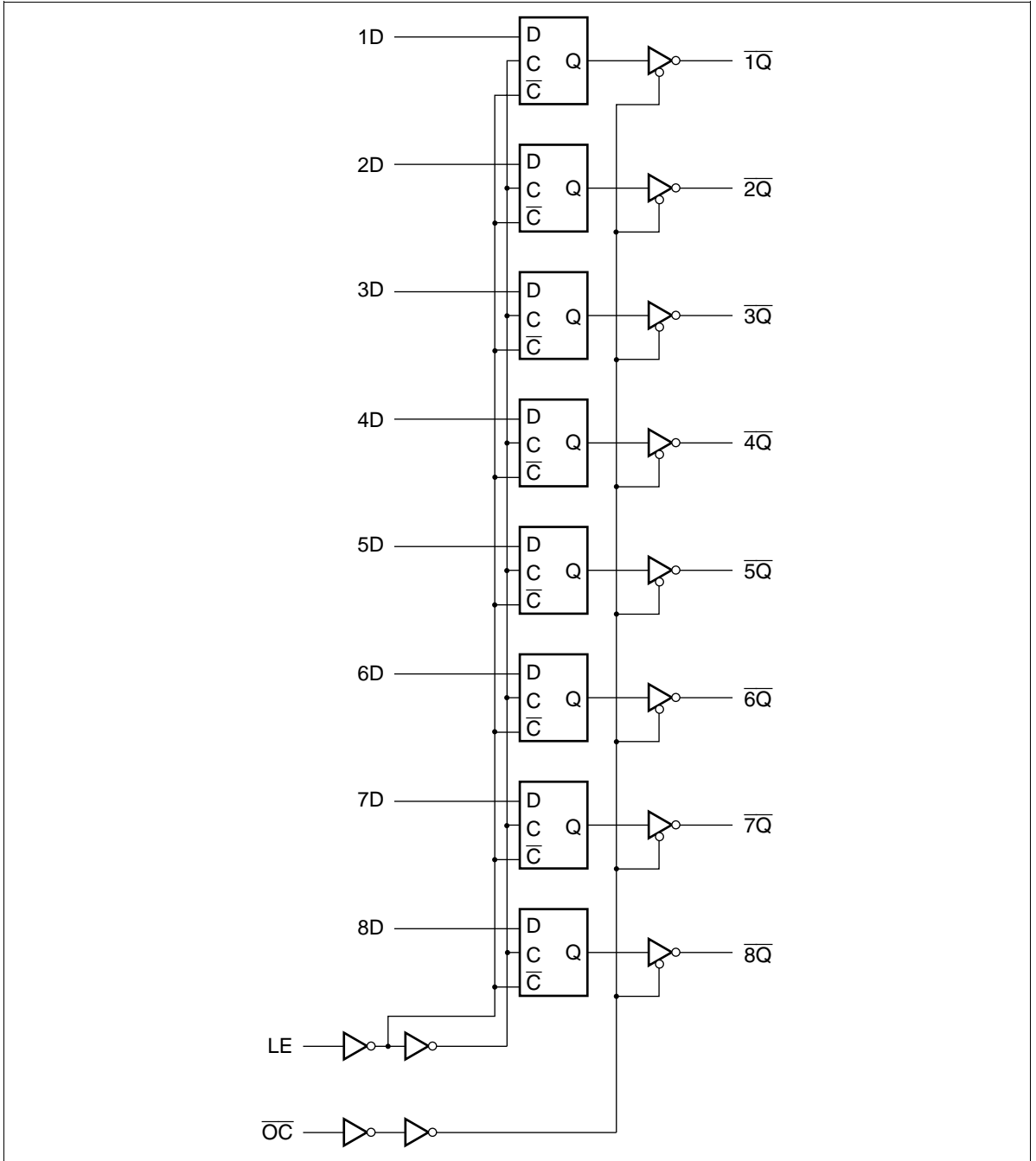


**Absolute Maximum Ratings**

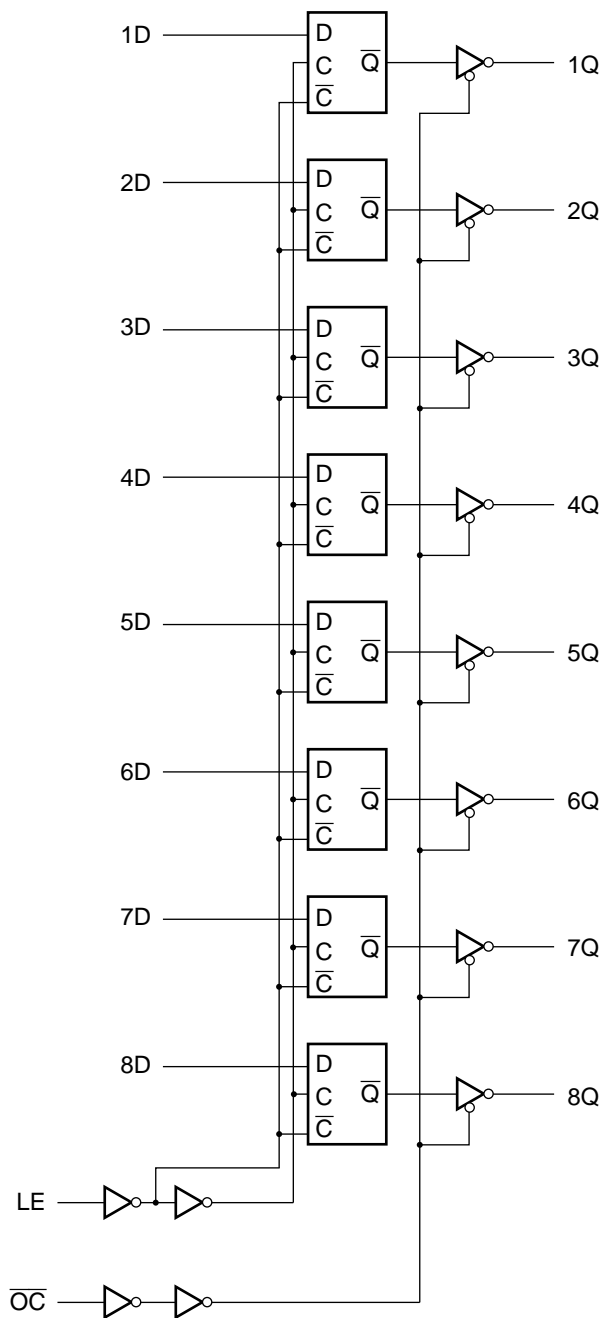
Item	Symbol	Rating	Unit
Supply voltage range	$V_{CC}$	-0.5 to +7.0	V
Input voltage	$V_{IN}$	-0.5 to $V_{CC} + 0.5$	V
Output voltage	$V_{OUT}$	-0.5 to $V_{CC} + 0.5$	V
Output current	$I_{OUT}$	$\pm 35$	mA
DC current drain per $V_{CC}$ , GND	$I_{CC}$ , $I_{GND}$	$\pm 75$	mA
DC input diode current	$I_{IK}$	$\pm 20$	mA
DC output diode current	$I_{OK}$	$\pm 20$	mA
Power Dissipation per package	$P_T$	500	mW
Storage temperature	$T_{stg}$	-65 to +150	$^{\circ}C$

## Block Diagram

### HD74HC563



HD74HC573



## DC Characteristics

Item	Symbol	V <sub>CC</sub> (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Input voltage	V <sub>IH</sub>	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V <sub>IL</sub>	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V <sub>OH</sub>	2.0	1.9	2.0	—	1.9	—	V	Vin = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I <sub>OH</sub> = -6 mA
		6.0	5.68	—	—	5.63	—			I <sub>OH</sub> = -7.8 mA
		6.0	—	0.0	0.1	—	0.1			V
	4.5	—	0.0	0.1	—	0.1				
	6.0	—	0.0	0.1	—	0.1				
	4.5	—	—	0.26	—	0.33	I <sub>OL</sub> = 6 mA			
	6.0	—	—	0.26	—	0.33	I <sub>OL</sub> = 7.8 mA			
Off-state output current	I <sub>OZ</sub>	6.0	—	—	±0.5	—	±5.0	μA	Vin = V <sub>IH</sub> or V <sub>IL</sub> , Vout = V <sub>CC</sub> or GND	
Input current	I <sub>in</sub>	6.0	—	—	±0.1	—	±1.0	μA	Vin = V <sub>CC</sub> or GND	
Quiescent supply current	I <sub>CC</sub>	6.0	—	—	4.0	—	40	μA	Vin = V <sub>CC</sub> or GND, Iout = 0 μA	

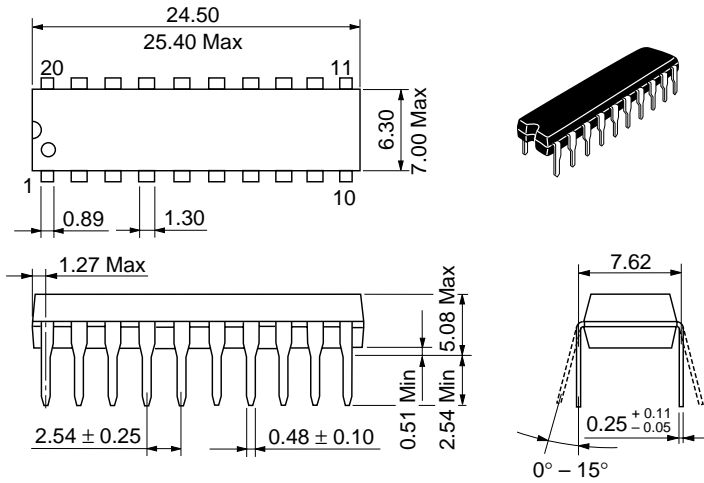


AC Characteristics ( $C_L = 50$  pF, Input  $t_r = t_f = 6$  ns)

Item	Symbol	$V_{CC}$ (V)	$T_a = 25^\circ\text{C}$		$T_a = -40$ to $+85^\circ\text{C}$		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Propagation delay time	$t_{PLH}$	2.0	—	—	110	—	140	ns	Data to $\bar{Q}$	
	$t_{PHL}$	4.5	—	11	22	—	28			
		6.0	—	—	19	—	24			
		$t_{PLH}$	2.0	—	—	115	—	145	ns	Clock to $\bar{Q}$
		$t_{PHL}$	4.5	—	13	23	—	29		
			6.0	—	—	20	—	25		
Output enable time	$t_{ZH}$	2.0	—	—	150	—	190	ns		
	$t_{ZL}$	4.5	—	14	30	—	38			
		6.0	—	—	26	—	33			
Output disable time	$t_{HZ}$	2.0	—	—	150	—	190	ns		
	$t_{LZ}$	4.5	—	15	30	—	38			
		6.0	—	—	26	—	33			
Setup time	$t_{su}$	2.0	75	—	—	90	—	ns		
		4.5	15	2	—	19	—			
		6.0	13	—	—	16	—			
Hold time	$t_h$	2.0	5	—	—	5	—	ns		
		4.5	5	-1	—	5	—			
		6.0	5	—	—	5	—			
Pulse width	$t_w$	2.0	80	—	—	100	—	ns		
		4.5	16	4	—	20	—			
		6.0	14	—	—	17	—			
Output rise/fall time	$t_{TLH}$	2.0	—	—	60	—	75	ns		
	$t_{THL}$	4.5	—	4	12	—	15			
		6.0	—	—	10	—	13			
Input capacitance	$C_{in}$	—	—	5	10	—	10	pF		

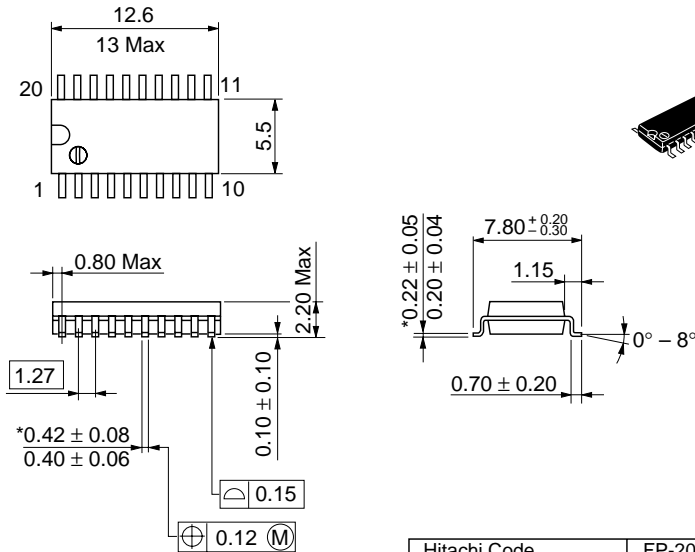
## Package Dimensions

Unit: mm



Hitachi Code	DP-20N
JEDEC	—
EIAJ	Conforms
Mass (reference value)	1.26 g

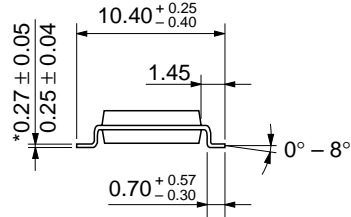
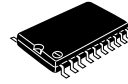
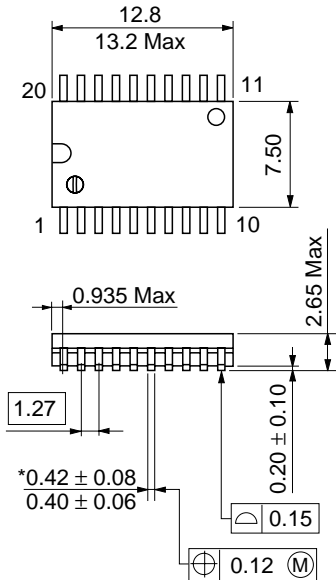
Unit: mm



\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	FP-20DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.31 g

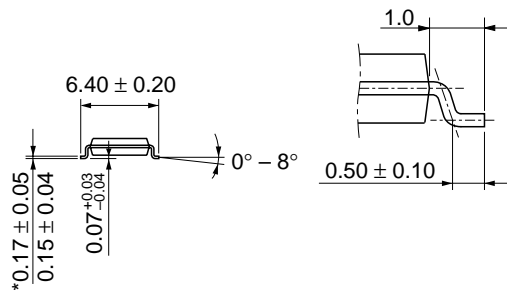
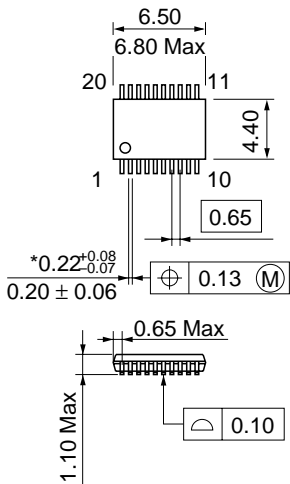
Unit: mm



\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	FP-20DB
JEDEC	Conforms
EIAJ	—
Mass (reference value)	0.52 g

Unit: mm



\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	TTP-20DA
JEDEC	—
EIAJ	—
Mass (reference value)	0.07 g

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# HITACHI

## Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan  
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL       NorthAmerica       : <http://semiconductor.hitachi.com/>  
          Europe                : <http://www.hitachi-eu.com/hel/ecg>  
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## For further information write to:

Hitachi Semiconductor  
(America) Inc.  
179 East Tasman Drive,  
San Jose, CA 95134  
Tel: <1> (408) 433-1990  
Fax: <1> (408) 433-0223

Hitachi Europe GmbH  
Electronic Components Group  
Dornacher Straße 3  
D-85622 Feldkirchen, Munich  
Germany  
Tel: <49> (89) 9 9180-0  
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.  
Electronic Components Group.  
Whitebrook Park  
Lower Cookham Road  
Maidenhead  
Berkshire SL6 8YA, United Kingdom  
Tel: <44> (1628) 585000  
Fax: <44> (1628) 585160

Hitachi Asia Ltd.  
Hitachi Tower  
16 Collyer Quay #20-00,  
Singapore 049318  
Tel : <65>-538-6533/538-8577  
Fax : <65>-538-6933/538-3877  
URL : <http://www.hitachi.com.sg>

Hitachi Asia Ltd.  
(Taipei Branch Office)  
4/F, No. 167, Tun Hwa North Road,  
Hung-Kuo Building,  
Taipei (105), Taiwan  
Tel : <886>-(2)-2718-3666  
Fax : <886>-(2)-2718-8180  
Telex : 23222 HAS-TP  
URL : <http://www.hitachi.com.tw>

Hitachi Asia (Hong Kong) Ltd.  
Group III (Electronic Components)  
7/F., North Tower,  
World Finance Centre,  
Harbour City, Canton Road  
Tsim Sha Tsui, Kowloon,  
Hong Kong  
Tel : <852>-(2)-735-9218  
Fax : <852>-(2)-730-0281  
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